

# SN54HCT74, SN74HCT74 DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS WITH CLEAR AND PRESET

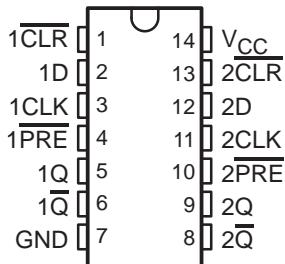
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- Operating Voltage Range of 4.5 V to 5.5 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 40- $\mu$ A Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 17 ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- Inputs Are TTL-Voltage Compatible

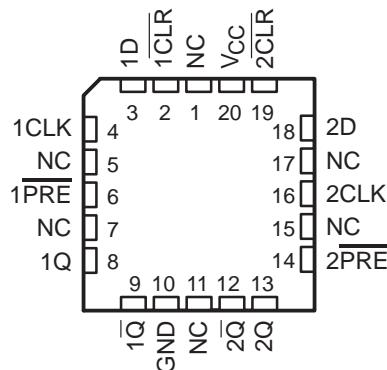
## description/ordering information

The 'HCT74 devices contain two independent D-type positive-edge-triggered flip-flops. A low level at the preset ( $\overline{PRE}$ ) or clear ( $\overline{CLR}$ ) inputs sets or resets the outputs, regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) input meeting the setup time requirements are transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of CLK. Following the hold-time interval, data at the D input may be changed without affecting the levels at the outputs.

**SN54HCT74 . . . J OR W PACKAGE**  
**SN74HCT74 . . . D, DB, N, NS, OR PW PACKAGE**  
(TOP VIEW)



**SN54HCT74 . . . FK PACKAGE**  
(TOP VIEW)



NC – No internal connection

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HCT74N	SN74HCT74N
	SOIC – D	Tube of 50	SN74HCT74D	HCT74
		Reel of 2500	SN74HCT74DR	
		Reel of 250	SN74HCT74DT	
	SOP – NS	Reel of 2000	SN74HCT74NSR	HCT74
	SSOP – DB	Reel of 2000	SN74HCT74DBR	HT74
	TSSOP – PW	Tube of 90	SN74HCT74PW	HT74
		Reel of 2000	SN74HCT74PWR	
		Reel of 250	SN74HCT74PWT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HCT74J	SNJ54HCT74J
	CFP – W	Tube of 150	SNJ54HCT74W	SNJ54HCT74W
	LCCC – FK	Tube of 55	SNJ54HCT74FK	SNJ54HCT74FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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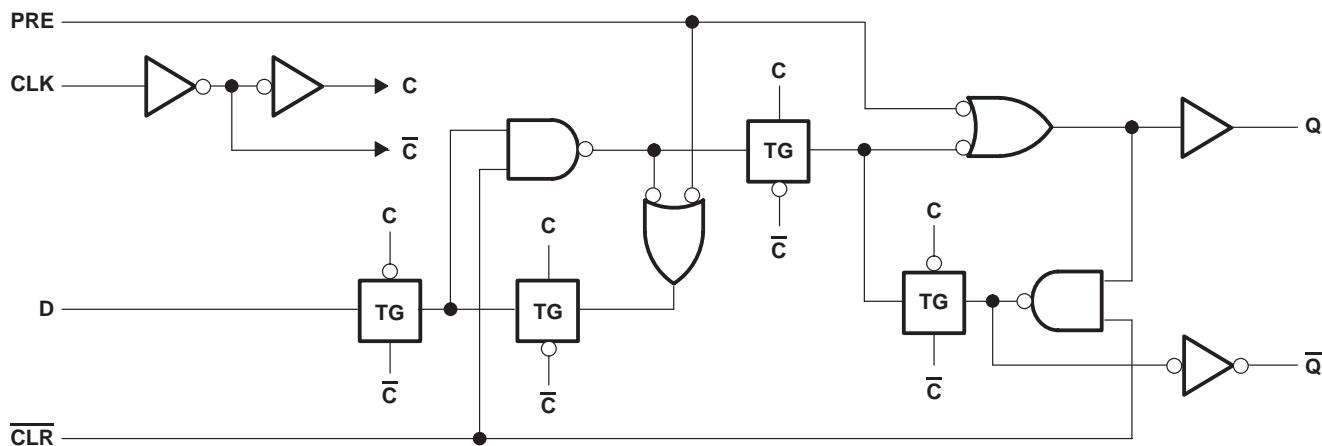
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## FUNCTION TABLE

INPUTS				OUTPUT	
PRE	CLR	CLK	D	Q	$\bar{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	$H^\dagger$	$H^\dagger$
H	H	$\uparrow$	H	H	L
H	H	$\uparrow$	L	L	H
H	H	L	X	$Q_0$	$\bar{Q}_0$

<sup>†</sup> This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

## logic diagram (positive logic)



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡**

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

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**DUAL D-TYPE POSITIVE-EDGE-TRIGGERED FLIP-FLOPS**  
**WITH CLEAR AND PRESET**

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**recommended operating conditions (see Note 3)**

			SN54HCT74			SN74HCT74			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2			2			V
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V			0.8			0.8	V
V <sub>I</sub>	Input voltage		0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
Δt/Δv	Input transition rise/fall time				500			500	ns
T <sub>A</sub>	Operating free-air temperature		-55	125		-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HCT74		SN74HCT74		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	4.5 V	4.4	4.499		4.4		4.4		V
			3.98	4.3		3.7		3.84		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	4.5 V	0.001	0.1		0.1		0.1		V
			0.17	0.26		0.4		0.33		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	5.5 V	±0.1	±100		±1000		±1000		nA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	5.5 V		4		80		40		μA
ΔI <sub>CC</sub> <sup>†</sup>	One input at 0.5 V or 2.4 V, Other inputs at 0 or V <sub>CC</sub>	5.5 V		1.4	2.4	3		2.9		mA
C <sub>i</sub>		4.5 V to 5.5 V		3	10	10		10		pF

<sup>†</sup>This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

**timing requirements over recommended operating free-air temperature range (unless otherwise noted)**

		V <sub>CC</sub>	T <sub>A</sub> = 25°C		SN54HCT74		SN74HCT74		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency	4.5 V		27		18		22	MHz
		5.5 V		30		20		24	
t <sub>w</sub>	Pulse duration	PRE or CLR low	4.5 V	16		24		20	ns
			5.5 V	14		21		18	
		CLK high or low	4.5 V	18		27		23	
			5.5 V	16		24		21	
t <sub>su</sub>	Setup time before CLK↑	Data	4.5 V	12		18		15	ns
			5.5 V	11		16		14	
		PRE or CLR inactive	4.5 V	0		0		0	
			5.5 V	0		0		0	
t <sub>h</sub>	Hold time, data after CLK↑	4.5 V	0		0		0		ns
		5.5 V	0		0		0		

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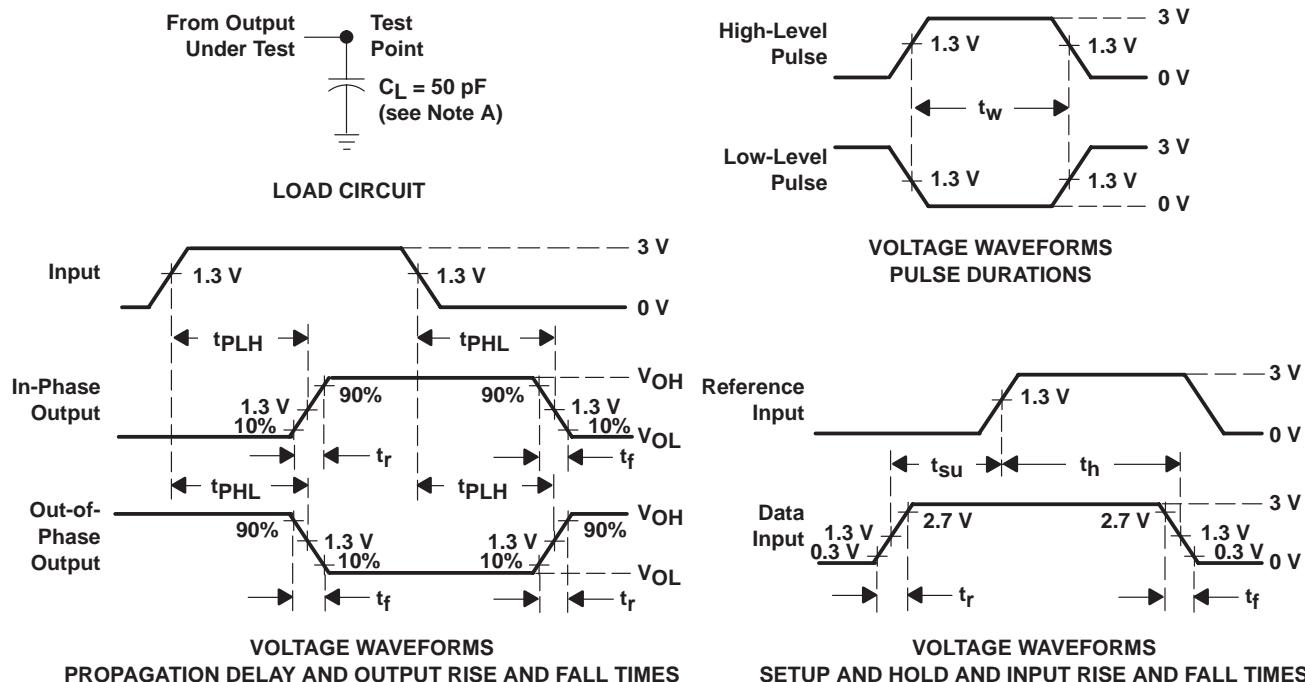
switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HCT74	SN74HCT74	UNIT
				MIN	TYP	MAX			
$f_{max}$			4.5 V	27	40	48	18	22	MHz
			5.5 V	30	46	53	20	24	
$t_{pd}$	$\overline{\text{PRE}}$ or $\overline{\text{CLR}}$	Q or $\overline{Q}$	4.5 V	21	35	53	44	40	ns
			5.5 V	17	31	48	35	31	
	CLK	Q or $\overline{Q}$	4.5 V	20	28	42	38	31	
			5.5 V	18	25	38	31	22	
$t_t$		Q or $\overline{Q}$	4.5 V	8	15	22	19	17	ns
			5.5 V	7	14	20	19	17	

## operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per flip-flop	No load	35	pF

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .  
C. For clock inputs,  $f_{max}$  is measured when the input duty cycle is 50%.  
D. The outputs are measured one at a time, with one input transition per measurement.  
E.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

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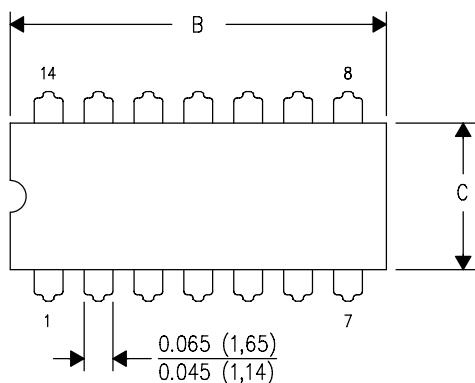
 **TEXAS  
INSTRUMENTS**

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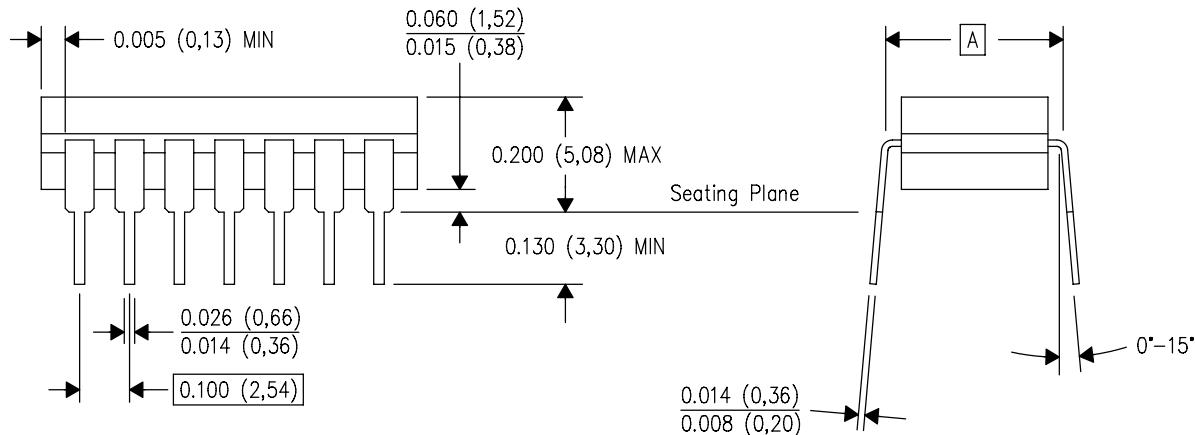
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS **\nDIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

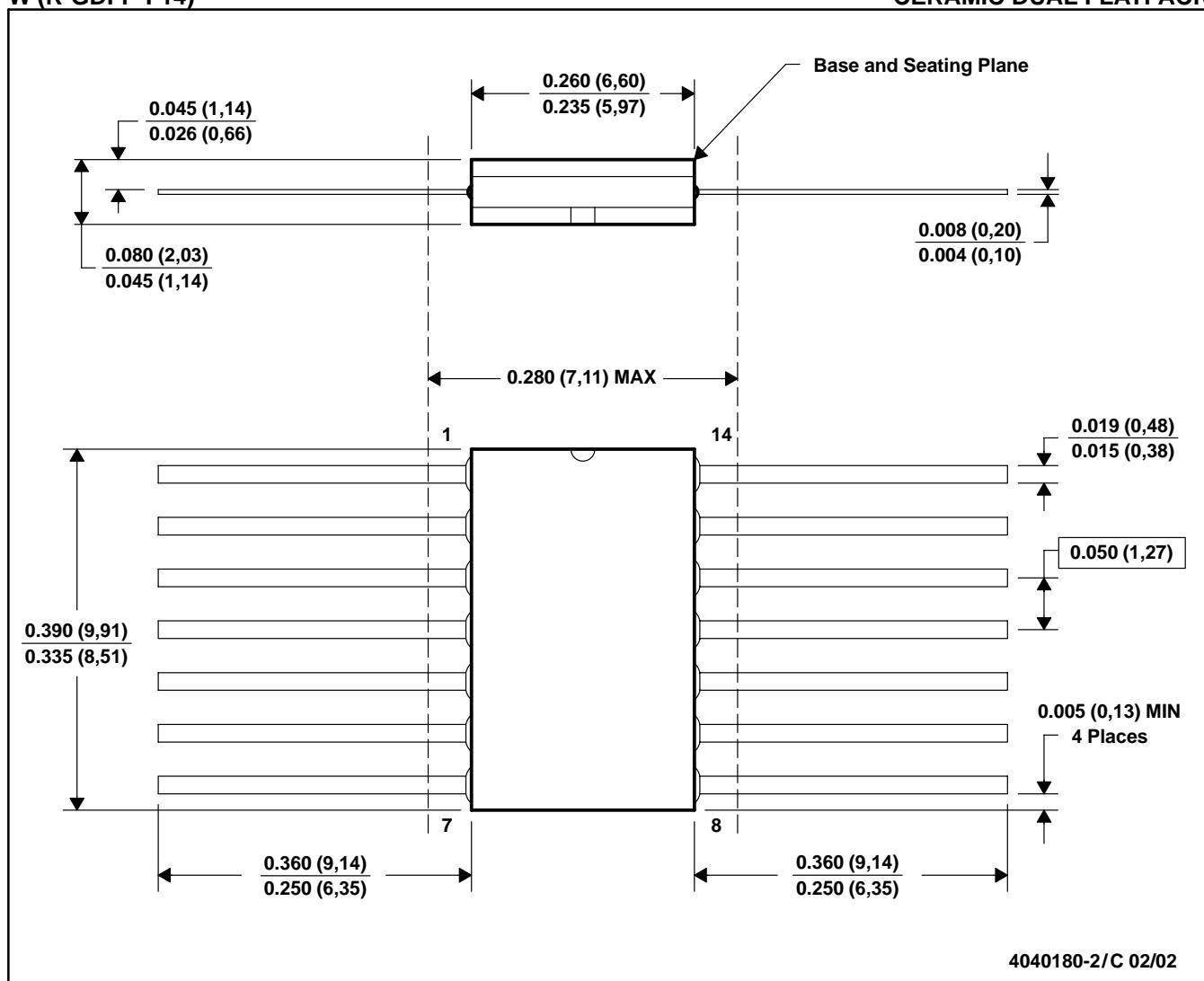


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



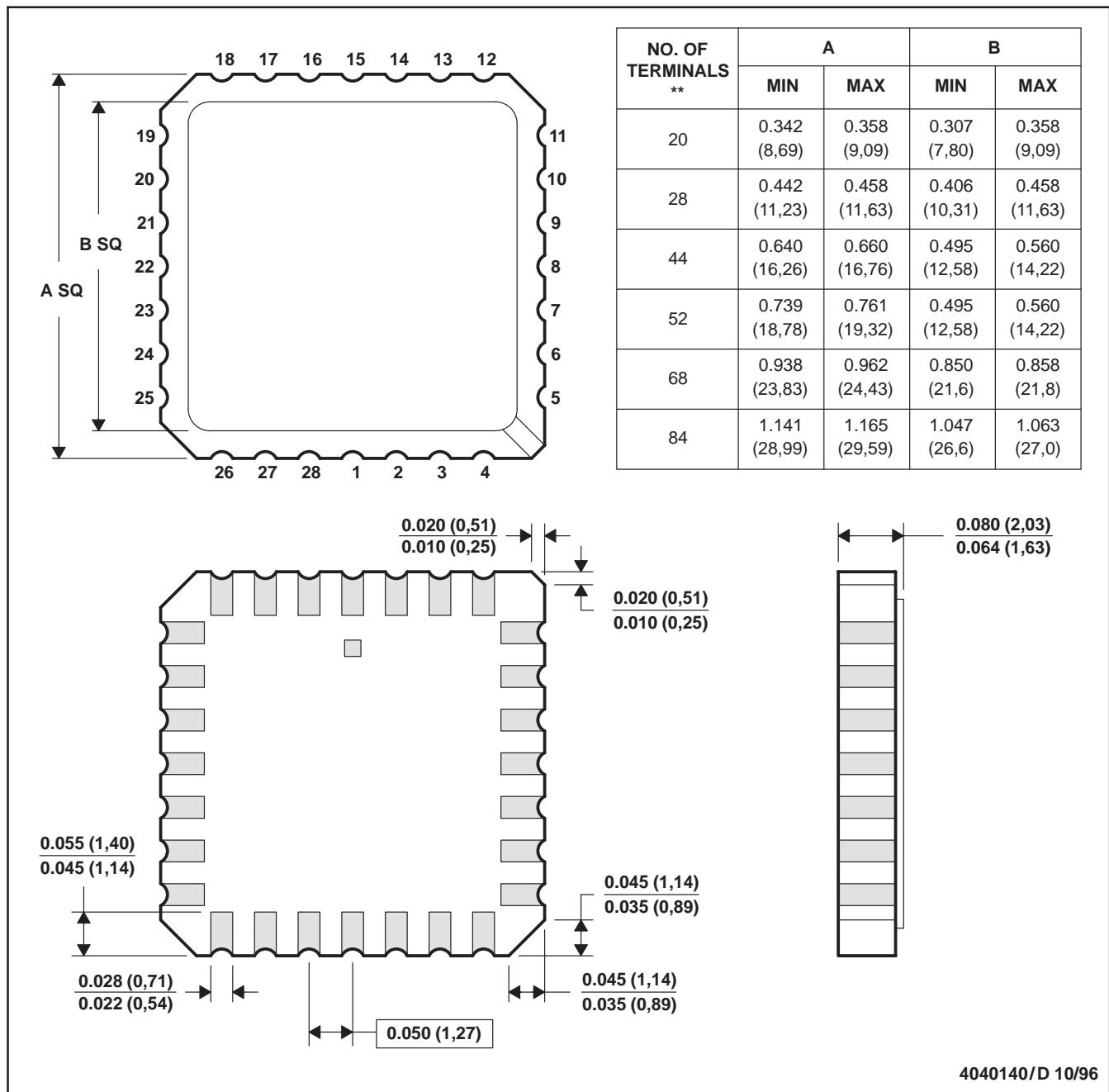
4040180-2/C 02/02

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only.
  - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

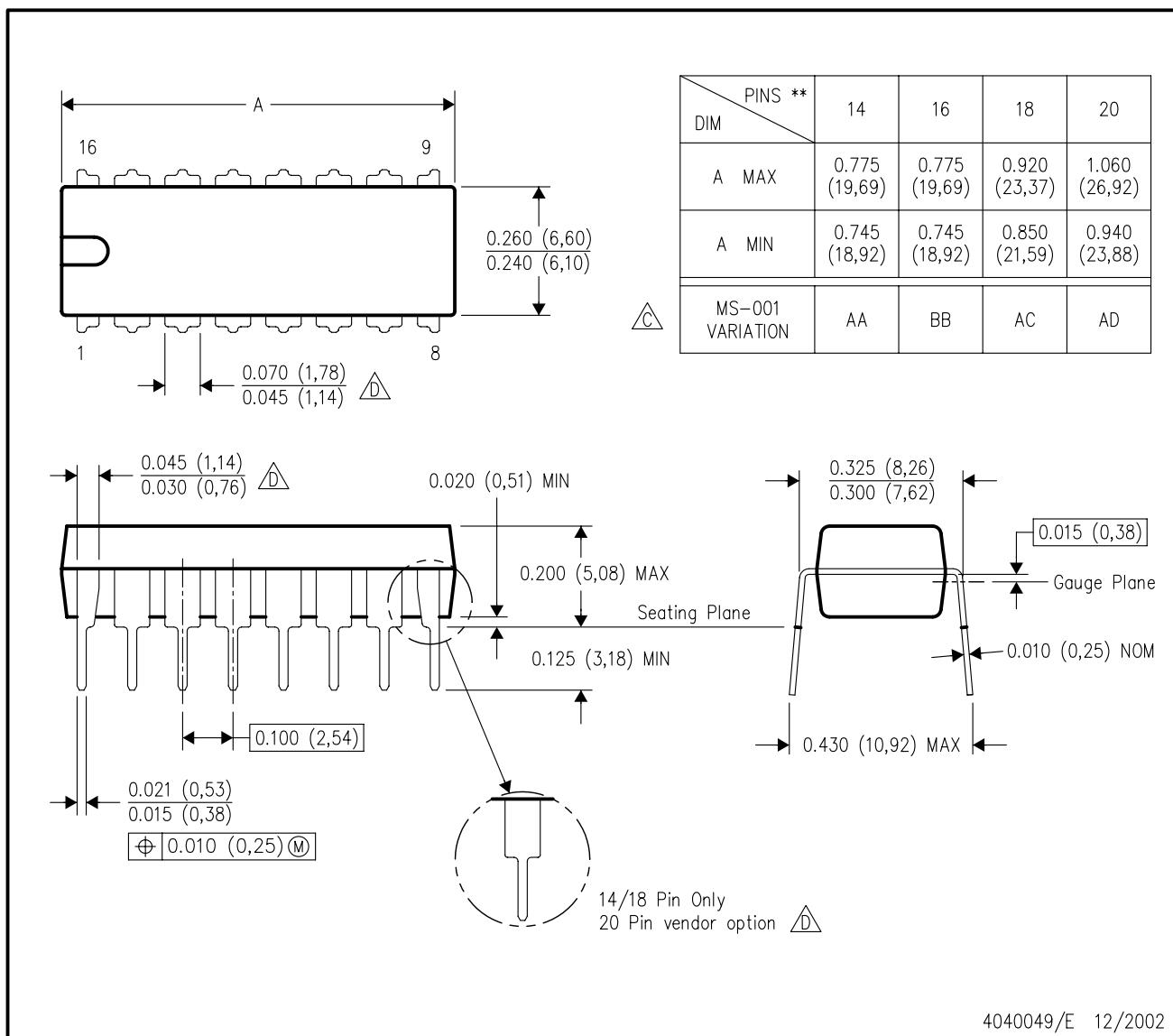
E. Falls within JEDEC MS-004

4040140/D 10/96

## N (R-PDIP-T\*\*)

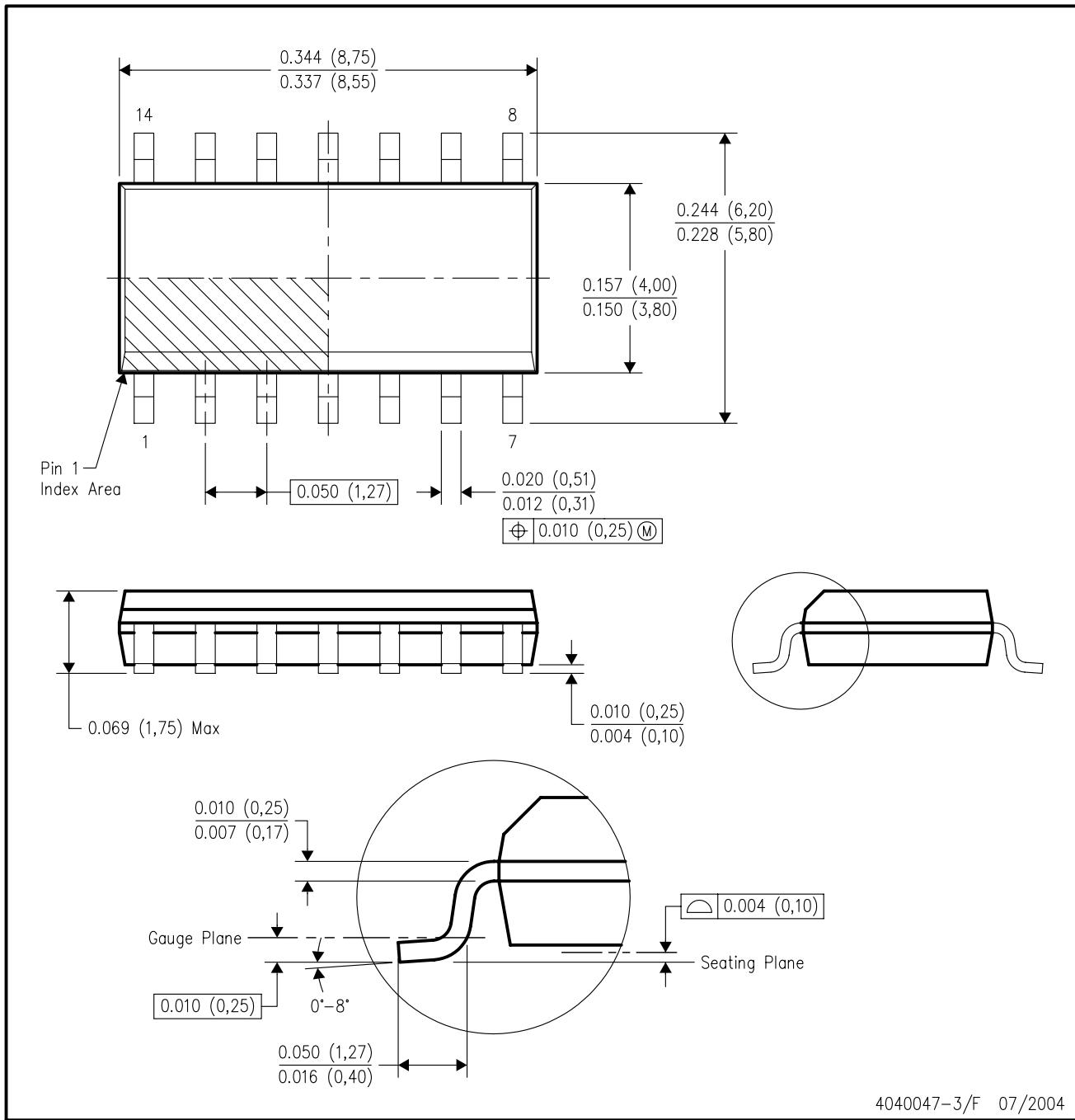
16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



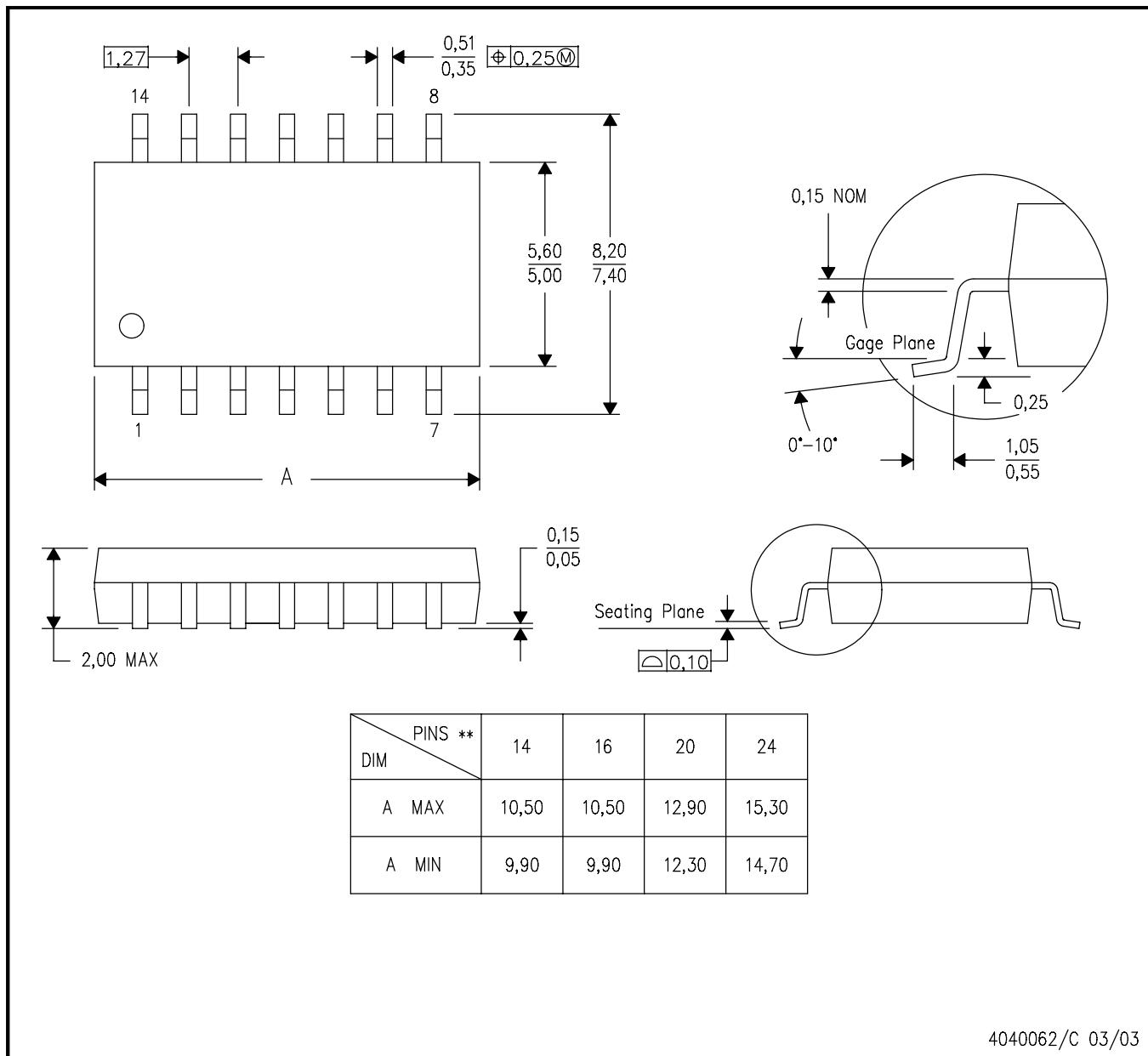
- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-012 variation AB.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**14-PINS SHOWN**

**PLASTIC SMALL-OUTLINE PACKAGE**

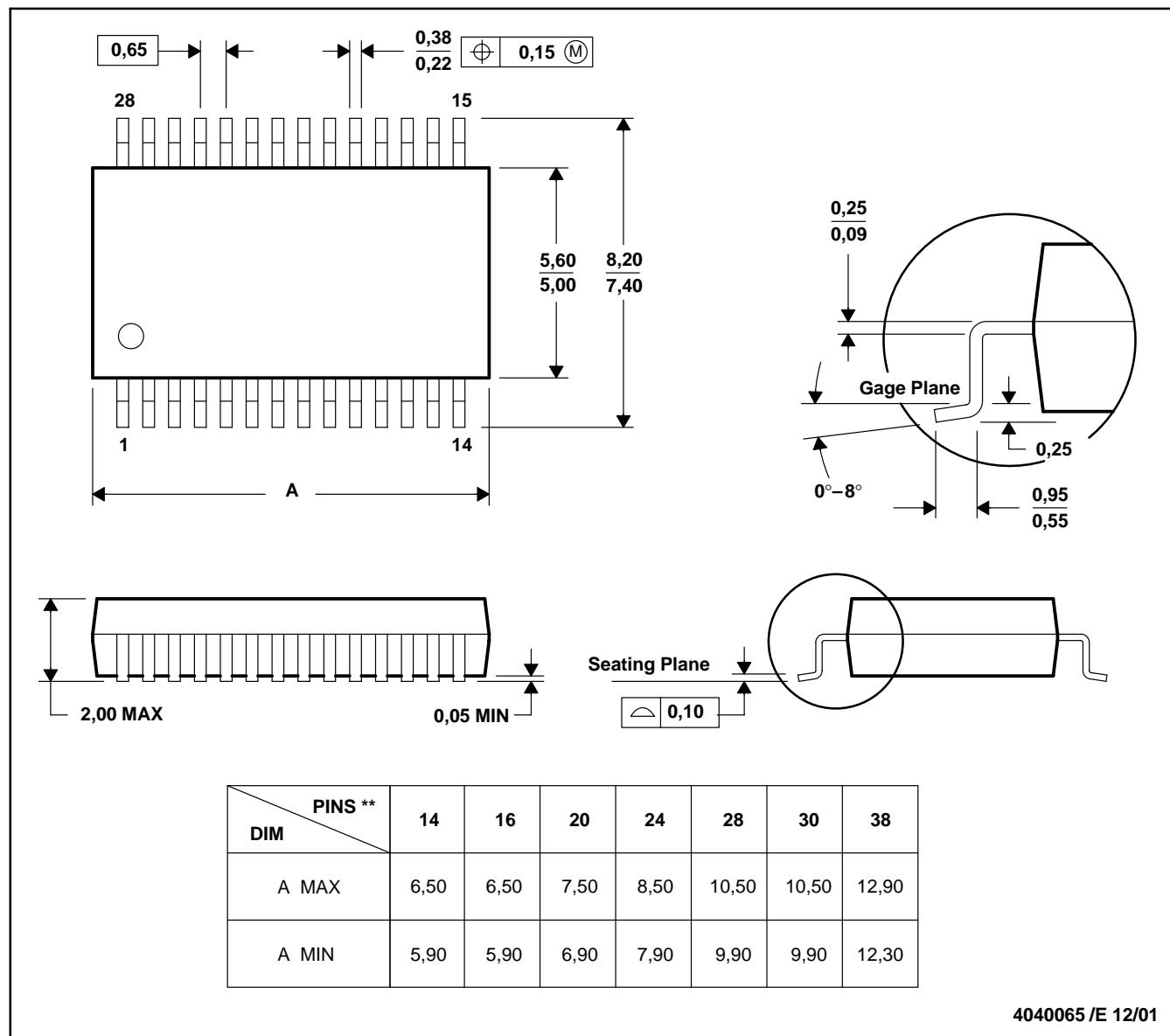


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN

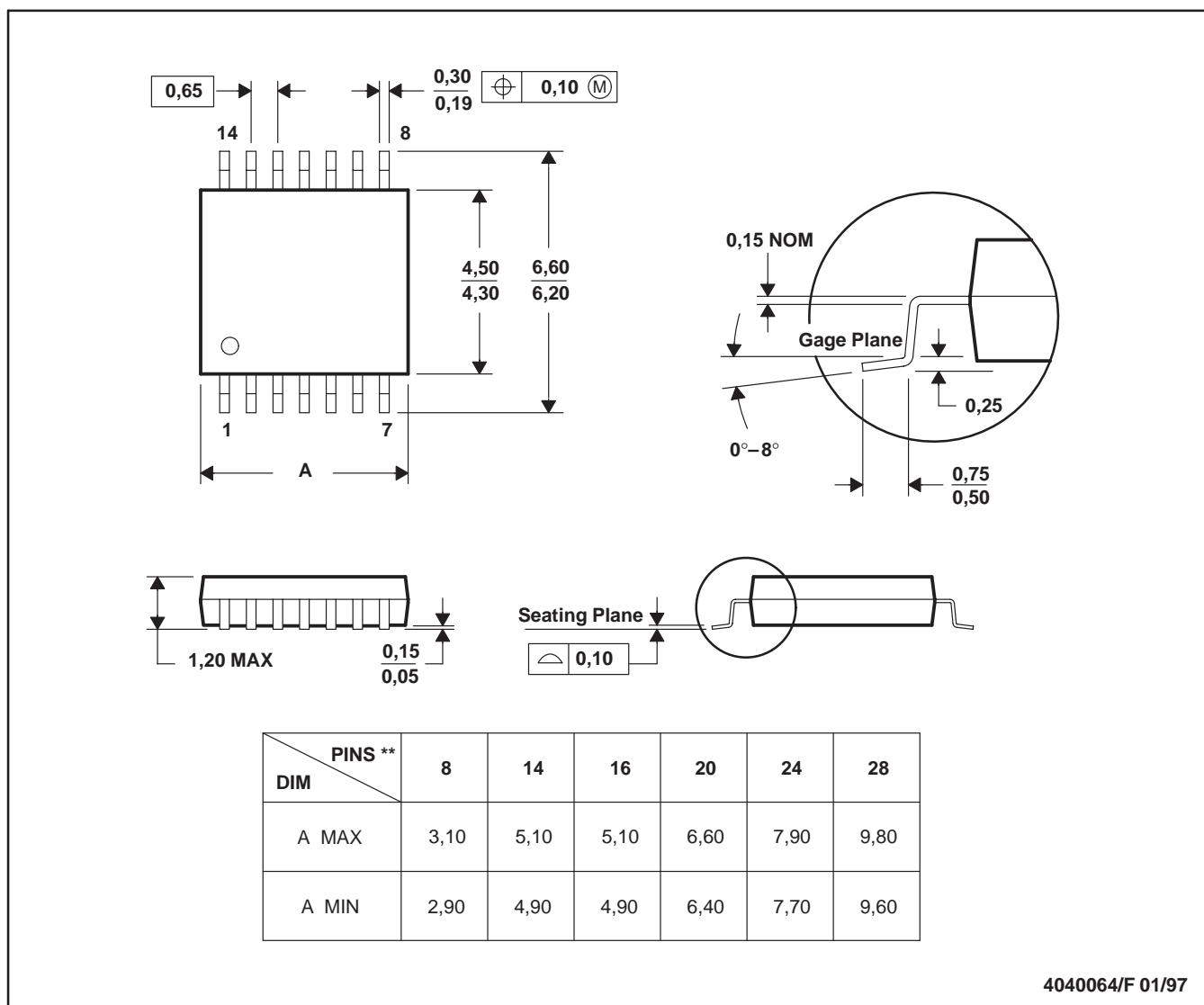


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
  - D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
  - Falls within JEDEC MO-153

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